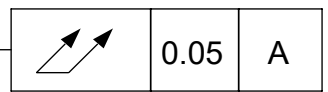
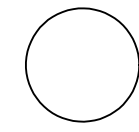
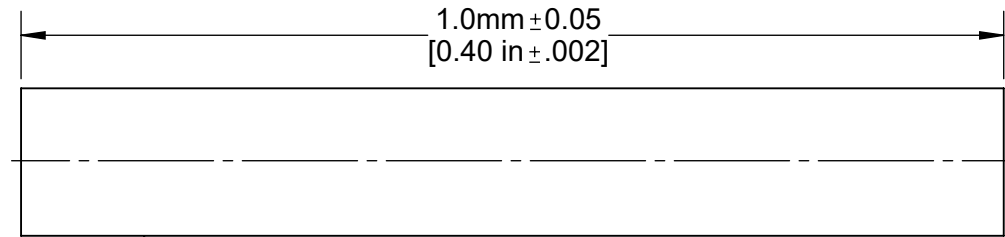
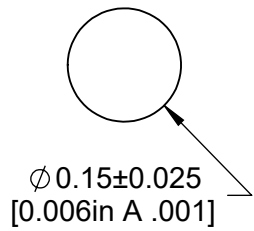


TOP

SIDE VIEW

END VIEW



MODEL



PART NUMBER SYSTEM				
CU194	G	6	X	40
<u>SERIES</u>	<u>PLATING</u>	<u>DIA</u>	<u>PACK</u>	<u>LENGTH</u>
COPPER ALLOY EFTEC C194	Ni Au	6 MIL 0.15mm	X=BULK W=WAFFLE	40 MIL 1.0mm

PLATING - SURFACE TREATMENT		
LAYER	METRIC	BSC
Ni	3.0µm Min	120 µ-inch Min
Au Flash	0.20µm Max	8 µ-inch Max

Physical Properties				
Coefficient of thermal expansion X 10 ⁻⁵ /°C	Thermal conductivity W/(m*k)	Electrical conductivity %IACS	Modulus of elasticity GPa	Density g/cm ³
17.4	260	65	121	8.8

NOTES:

1. DIMENSIONS IN MM (UNLESS OTHERWISE SPECIFIED).
2. TOLERANCE TO BE DEFINED.
3. BASE METAL EFTEC-194W COPPER ALLOY (C194).
4. ALLOY MASS% Cu97.4/ Fe2.4/ Zn0.13/ P0.04

APPROVALS	DATE	TopLine®			
DRAWN T. Au	10/4/2021				
ENG M. Hart	10/4/2021	TITLE CU194G6x40 ALLOY C194 PILLAR			
MFG		SCALE 30:1	SIZE A	DRAWING NO. 650640	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 1
CUST					
REVISED					